EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	140	(semiconductor or wafer or substrate) and (active near4 region) and "nFET" and "pFET" and (gate near4 electrode)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 10:59
L2	1	(semiconductor or wafer or substrate) and (active near4 region) and "nFET" and "pFET" and (gate near4 electrode) and (bond$4 near4 (semiconductor or wafer or substrate)) and (open$4 or via or trench or hole) and (implant$4 near4 oxygen) and (anneal or heat or thermal) and stress and (current near8 flow)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 11:05
L3	4	(semiconductor or wafer or substrate) and (active near4 region) and "nFET" and "pFET" and (gate near4 electrode) and (bond$4 near4 (semiconductor or wafer or substrate)) and (open$4 or via or trench or hole) and stress and (current near8 flow)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 11:56
L4	13	(semiconductor or wafer or substrate) and (active near4 region) and "nFET" and "pFET" and (gate near4 electrode) and (bond$4 near4 (semiconductor or wafer or substrate)) and (open$4 or via or trench or hole) and stress	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 11:57
L5	9	(semiconductor or wafer or substrate) and (active near4 region) and "nFET" and "pFET" and (gate near4 electrode) and (bond$4 near4 (semiconductor or wafer or substrate)) and (open$4 or via or trench or hole) and stress and direction	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 13:47
L6	6	(semiconductor or wafer or substrate) and (active near4 region) and "nFET" and "pFET" and (gate near4 electrode) and (bond$4 near4 (semiconductor or wafer or substrate)) and (implant$4 near4 oxygen)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 13:48

| L7 | 6 | (semiconductor or wafer or substrate) and (active near4 region) and "nFET" and "pFET" and (gate near4 electrode) and (bond$4 near4 (semiconductor or wafer or substrate)) and (implant$4 near4 oxygen) and (anneal or thermal or heat) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/09/21 13:48 |